LCCC - Issue #4 (Spring 2026)

Welcome to the Spring issue of the LCCC Newsletter!

The past months have **marked an important milestone for the Latvian Chip Competence Centre (LCCC)** and **the wider Baltic-Nordic semiconductor ecosystem**. From regional coordination meetings and international collaboration initiatives to the **successful organisation of the first Riga Chip Summit 2026**, LCCC continues strengthening Latvia's role within the European semiconductor landscape.

This edition highlights recent activities that brought together industry leaders, researchers, startups, policymakers, and competence centres from across Europe to discuss the future of semiconductors, microelectronics, photonics, AI, IoT, skills development, and innovation support. A particular highlight was **Riga Chip Summit 2026**, which welcomed **more than 200 participants from 23 countries** and became the first dedicated semiconductor summit organised in Latvia.

In this issue, you will also find **updates** from the **Baltic-Nordic CCC Quarterly Meeting**, recent collaboration initiatives, **upcoming European events, training opportunities**, and **networking activities** relevant to the semiconductor and deep-tech community.

Thank you for following the activities of the **Latvian Chip Competence Centre** as we continue building a stronger, more connected, and innovation-driven semiconductor ecosystem in Latvia and across Europe

Recent events

Riga Chip Summit

On 13 May 2026, the **Latvian Chip Competence Centre organised Riga Chip Summit 2026** – **the first dedicated semiconductor summit ever held in Latvia**. The event became an important milestone for the Baltic and European semiconductor ecosystem, bringing together **more than 200 participants from 23 countries**, including industry leaders, researchers, startups, investors, policymakers, academia, and innovation ecosystem representatives from across the Baltics, Nordics, and Europe.

Throughout the summit, participants discussed **the future of semiconductors, photonics, AI, IoT, chip design, commercialization pathways, funding opportunities, and the development of the European semiconductor ecosystem under the Chips Joint Undertaking (Chips JU).**

One of the most significant moments of the summit was the **signing of a Memorandum of Understanding between the Latvian Chip Competence Centre and the LMT**

Group, marking a major step toward stronger collaboration between research and industry in Latvia.

The cooperation focuses on research and development activities related to low-power mobile IoT connectivity chips and strengthening Latvia's capacity to develop internationally competitive high-tech products.

The summit programme featured internationally recognised experts, who addressed topics such as semiconductor ecosystem development, chip design platforms, funding opportunities, intellectual property protection, and technology readiness development.

Riga Chip Summit 2026 was **organised by the Latvian Chip Competence Centre** in cooperation with the **LMT Group, Lithuanian Chips Competence Centre (ChipsC2-LT)**, and **Estonian Chips Competence Center (KIIP)**.

More information and event highlights are available on the Latvian Chip Competence Centre LinkedIn page:
https://www.linkedin.com/showcase/latvian-chip-competence-centre/

Photos from the event can be found **here**.

Baltic-Nordic CCC Quarterly Meeting in Riga

On 12 May 2026, the **Latvian Chip Competence Centre hosted the Baltic-Nordic 2nd 2026 Quarterly Meeting for Baltic and Nordic Chip Competence Centres (CCCs)** at Riga Technical University.

The meeting brought together **representatives from Denmark, Sweden, Finland, Norway, Lithuania, Estonia and Latvia**, together with additional ecosystem stakeholders, to strengthen regional collaboration within the semiconductor ecosystem. Throughout the day, participants exchanged experiences, discussed current challenges, and worked together on defining concrete next steps for future cooperation.

The programme included **strategic discussions with the Nordic-Baltic management group, focus group breakout sessions, action plan presentations, and a visit to RTU laboratories.** Particular attention was devoted to long-term collaboration between competence centres, support mechanisms for startups and SMEs, ecosystem development, education initiatives, and joint communication activities.

Participants discussed business mentoring programmes, entrepreneurship support models, Nordic collaboration opportunities, and strategic sectors such as defence, drones, AI and dual-use technologies. Discussions also focused on how competence centres can better support startups and SMEs moving towards chip development and commercialization.

The communications focus group **agreed to establish regular monthly coordination meetings between Baltic and Nordic CCCs**, including a rotating facilitator model and shared communication activities. Participants discussed common communication challenges, internal collaboration between work packages, content sharing, and coordinated LinkedIn activities to improve visibility across the ecosystem.

Technology discussions focused on industry priorities, cleanroom mapping across the region, pilot line accessibility, intellectual property approaches, and practical support for SMEs entering semiconductor development. Participants also explored opportunities for shared infrastructure visibility and stronger cross-border technology collaboration.

The skills and education group discussed joint educational activities, including workshops, summer schools, hackathons, and future training initiatives. Participants also agreed on improving coordination around Chips JU calls and developing joint activities for 2027 focused on semiconductor skills development and ecosystem growth.

The meeting demonstrated the **growing importance of Baltic-Nordic collaboration in strengthening the regional semiconductor ecosystem** and building coordinated support structures for research, innovation and industry across Europe.

Upcoming Events

The Sensor Decade 2026

🗓️ June 3 & 4, 2026

📍 Ole-Johan Dahls Hus, Oslo, Norway

🔗 **Registration**

The Sensor Decade 2026 will bring together **researchers, industry representatives, policymakers, and technology innovators** to explore the rapidly expanding sensor value chain and its role in Europe's technological transformation.

The **event will focus on key societal and technological challenges**, including climate and environmental monitoring, healthcare and medtech, autonomous systems and robotics, as well as emerging fields such as quantum technologies, photonics, and nanotechnology. Discussions will cover the full spectrum of enabling technologies – from sensor materials and chip microfabrication to AI-enhanced sensing and sustainable technology solutions.

APECS Pilot Line Roadshow

🗓️ June 8, 2026

📍 Stockholm, Sweden

🔗 **Registration**

The Swedish Chip Competence Center (SCCC) and the APECS Pilot Line will host an exclusive networking reception. **The event will bring together representatives from the Nordic semiconductor ecosystem** for an evening of networking, keynote presentations, and discussions on advanced packaging, heterogeneous integration, and chiplet technologies within the framework of the EU Chips Act. Participants will also learn more about the APECS Pilot Line and the services and support provided by the Swedish Chips Competence Centre.

20th Silicon Saxony Days

🗓️ 15 – 17 June 2026

📍 International Airport Dresden, Germany

🔗 **Registration**

Silicon Saxony Days 2026 will bring together **Europe's high-tech community** for three days of exchange, collaboration, and networking in Dresden, Germany. As **one of Europe's leading semiconductor and microelectronics events**, the conference connects industry, research organisations, startups, policymakers, and technology innovators from across the entire value chain.

The programme will **focus on semiconductors, AI, quantum technologies, advanced manufacturing, cloud and software-enabled systems, digital infrastructure, and sustainable industrial transformation**. In addition to keynote sessions and panel discussions, the event will feature exhibitions, B2B matchmaking, and networking opportunities designed to foster new collaborations and innovation projects across Europe's high-tech ecosystem.

Brno Summer School: Chip Design & Semiconductor Technologies

🗓️ online sessions from September 2–4, 2026

🗓️ on-site programme from September 7–11 2026

📍 Brno University of Technology, Czech Republic

🔗 **Registration**

The Summer School 2026: Chip Design and Semiconductor Technologies will **provide students with an intensive learning experience focused on semiconductor technologies, chip design, and microelectronics**. Combining online sessions with an on-site programme in Brno, the summer school will cover CMOS fundamentals, analog circuit design, simulation and verification using professional tools, as well as hands-on activities in cleanroom and microscopy laboratories.

Designed for students in microelectronics, electrical engineering, and related fields, the programme also offers opportunities for international collaboration, networking, and knowledge exchange with experts and peers from across Europe.

Nordic Chip Summit 2026

🗓️ September 7–8, 2026

📍 Espoo, Finland

🔗 **Registration**

Nordic Chip Summit 2026 will bring together **leading experts, researchers, industry representatives, startups, and policymakers** to discuss the future of semiconductors, chip-based systems, and emerging deep-tech technologies in Europe.

Call for proposal

The **Chips for Europe** Initiative aims to build advanced technological capabilities and boost innovation across the European Union. Related OPEN and Coming Soon Calls can be found here.

🎙️ *Beyond Chips* Podcast by Chips Joint Undertaking

The Chips Joint Undertaking continues its official podcast – *Beyond Chips* – offering monthly insights into Europe's dynamic semiconductor ecosystem.

New episodes are released every first Wednesday of the month, featuring leading voices from industry, research, and policy. The podcast explores the strategic, technological, and economic dimensions of Europe's chips landscape.

🎧 Episodes 1–10 are already **available**, covering challenges, opportunities, and key innovations that are shaping the future of semiconductors in Europe.

Co-funded by the European Union
Chips JU
Latvian Council of Science
RTU RIGA TECHNICAL UNIVERSITY
UNIVERSITY OF LATVIA

This project is funded by the European Union Digital Europe Programme under Grant Agreement No 101217976. Views and opinions expressed are however those of the author(s) only and do not necessarily reflect those of the European Union or Chips Joint Undertaking. Neither the European Union nor the granting authority can be held responsible for them.